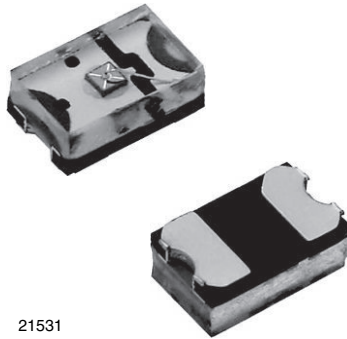




# High Speed Infrared Emitting Diode, 940 nm, GaAlAs Double Hetero



21531

## DESCRIPTION

VSMB1940X01 is an infrared, 940 nm emitting diode in GaAlAs Double Hetero technology with high radiant power and high speed, molded in clear, untinted 0805 plastic package for surface mounting (SMD).

## FEATURES

- Package type: surface mount
- Package form: 0805
- Dimensions (L x W x H in mm): 2 x 1.25 x 0.85
- AEC-Q101 qualified
- Peak wavelength:  $\lambda_p = 940$  nm
- High reliability
- High radiant power
- High radiant intensity
- High speed
- Angle of half sensitivity:  $\phi = \pm 60^\circ$
- Low forward voltage
- Suitable for high pulse current operation
- 0805 standard surface-mountable package
- Floor life: 168 h, MSL 3, acc. J-STD-020
- Lead (Pb)-free reflow soldering
- Compliant to RoHS Directive 2002/95/EC and in accordance to WEEE 2002/96/EC



## Note

\*\* Please see document "Vishay Material Category Policy": [www.vishay.com/doc?99902](http://www.vishay.com/doc?99902)

## APPLICATIONS

- High speed IR data transmission
- High power emitter for low space applications
- High performance transmissive or reflective sensors

PRODUCT SUMMARY				
COMPONENT	$I_e$ (mW/sr)	$\phi$ (deg)	$\lambda_p$ (nm)	$t_r$ (ns)
VSMB1940X01	6	$\pm 60$	940	15

## Note

- Test conditions see table "Basic Characteristics"

ORDERING INFORMATION			
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
VSMB1940X01	Tape and reel	MOQ: 3000 pcs, 3000 pcs/reel	0805

## Note

- MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS ( $T_{amb} = 25^\circ\text{C}$ , unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		$V_R$	5	V
Forward current		$I_F$	100	mA
Peak forward current	$t_p/T = 0.1, t_p = 100 \mu\text{s}$	$I_{FM}$	200	mA
Surge forward current	$t_p = 100 \mu\text{s}$	$I_{FSM}$	1	A
Power dissipation		$P_V$	160	mW
Junction temperature		$T_j$	100	$^\circ\text{C}$
Operating temperature range		$T_{amb}$	- 40 to + 85	$^\circ\text{C}$
Storage temperature range		$T_{stg}$	- 40 to + 100	$^\circ\text{C}$
Soldering temperature	$t \leq 5$ s, 2 mm from case	$T_{sd}$	260	$^\circ\text{C}$
Thermal resistance junction/ambient	J-STD-051, leads 7 mm, soldered on PCB	$R_{thJA}$	270	K/W

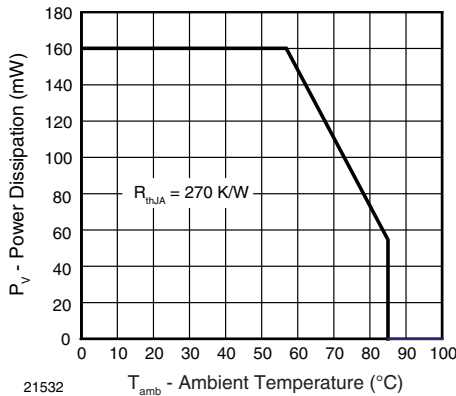


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

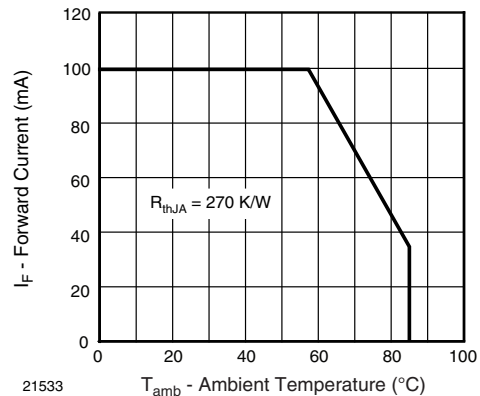


Fig. 1 - Forward Current Limit vs. Ambient Temperature

<b>BASIC CHARACTERISTICS</b> (T <sub>amb</sub> = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	I <sub>F</sub> = 100 mA, t <sub>p</sub> = 20 ms	V <sub>F</sub>	1.15	1.35	1.6	V
	I <sub>F</sub> = 1 A, t <sub>p</sub> = 100 μs	V <sub>F</sub>		2.2		V
Temperature coefficient of V <sub>F</sub>	I <sub>F</sub> = 1 mA	TK <sub>V<sub>F</sub></sub>		- 1.5		mV/K
	I <sub>F</sub> = 100 mA	TK <sub>V<sub>F</sub></sub>		- 1.1		mV/K
Reverse current	V <sub>R</sub> = 5 V	I <sub>R</sub>			10	μA
Junction capacitance	V <sub>R</sub> = 0 V, f = 1 MHz, E = 0 mW/cm <sup>2</sup>	C <sub>J</sub>		70		pF
Radiant intensity	I <sub>F</sub> = 100 mA, t <sub>p</sub> = 20 ms	I <sub>e</sub>	3	6	12	mW/sr
	I <sub>F</sub> = 1 A, t <sub>p</sub> = 100 μs	I <sub>e</sub>		60		mW/sr
Radiant power	I <sub>F</sub> = 100 mA, t <sub>p</sub> = 20 ms	φ <sub>e</sub>		40		mW
Temperature coefficient of radiant power	I <sub>F</sub> = 1 mA	TK <sub>φ<sub>e</sub></sub>		- 1.1		%/K
	I <sub>F</sub> = 100 mA	TK <sub>φ<sub>e</sub></sub>		- 0.51		%/K
Angle of half intensity		φ		± 60		deg
Peak wavelength	I <sub>F</sub> = 30 mA	λ <sub>p</sub>		940		nm
Spectral bandwidth	I <sub>F</sub> = 30 mA	Δλ		25		nm
Temperature coefficient of λ <sub>p</sub>	I <sub>F</sub> = 30 mA	TK <sub>λ<sub>p</sub></sub>		0.25		nm
Rise time	I <sub>F</sub> = 100 mA, 20 % to 80 %	t <sub>r</sub>		15		ns
Fall time	I <sub>F</sub> = 100 mA, 20 % to 80 %	t <sub>f</sub>		15		ns
Virtual source diameter		d		0.5		mm

**BASIC CHARACTERISTICS** ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)

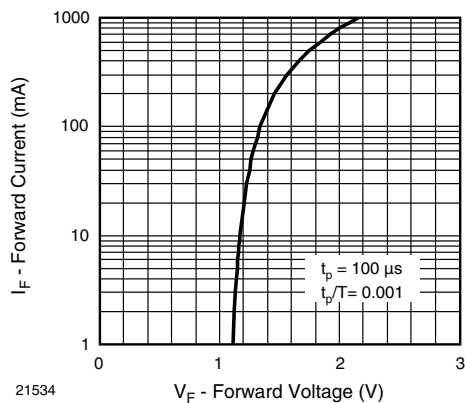


Fig. 2 - Forward Current vs. Forward Voltage

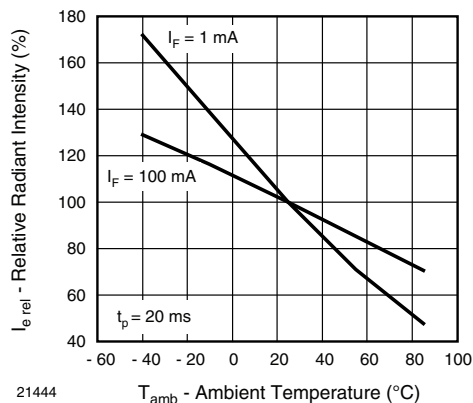


Fig. 5 - Relative Radiant Intensity vs. Ambient Temperature

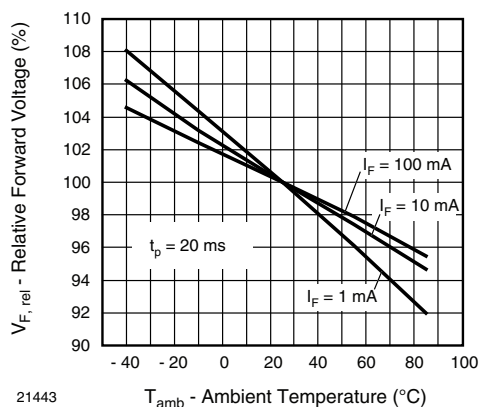


Fig. 3 - Relative Forward Voltage vs. Ambient Temperature

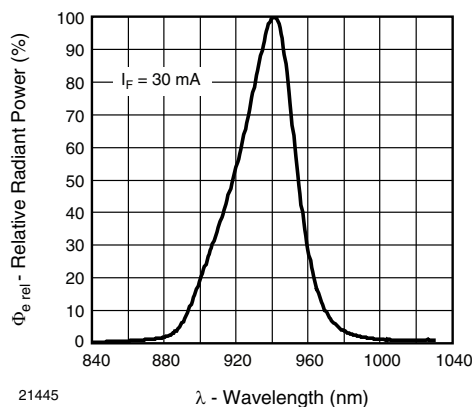


Fig. 6 - Relative Radiant Power vs. Wavelength

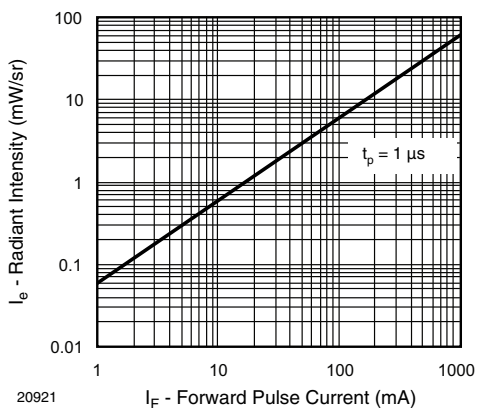


Fig. 4 - Radiant Intensity vs. Forward Current

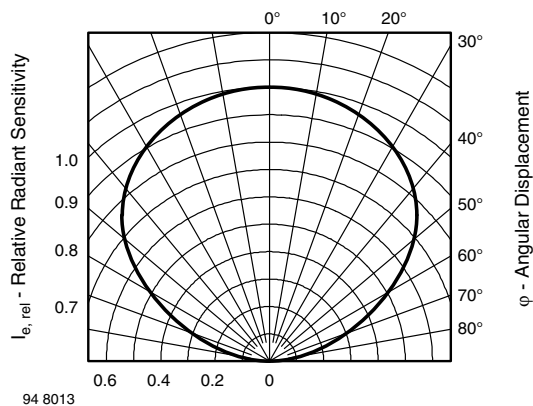


Fig. 7 - Relative Radiant Intensity vs. Angular Displacement

**REFLOW SOLDER PROFILE**

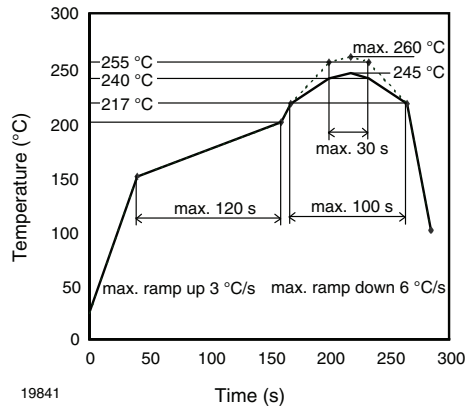


Fig. 8 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020

**DRYPACK**

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

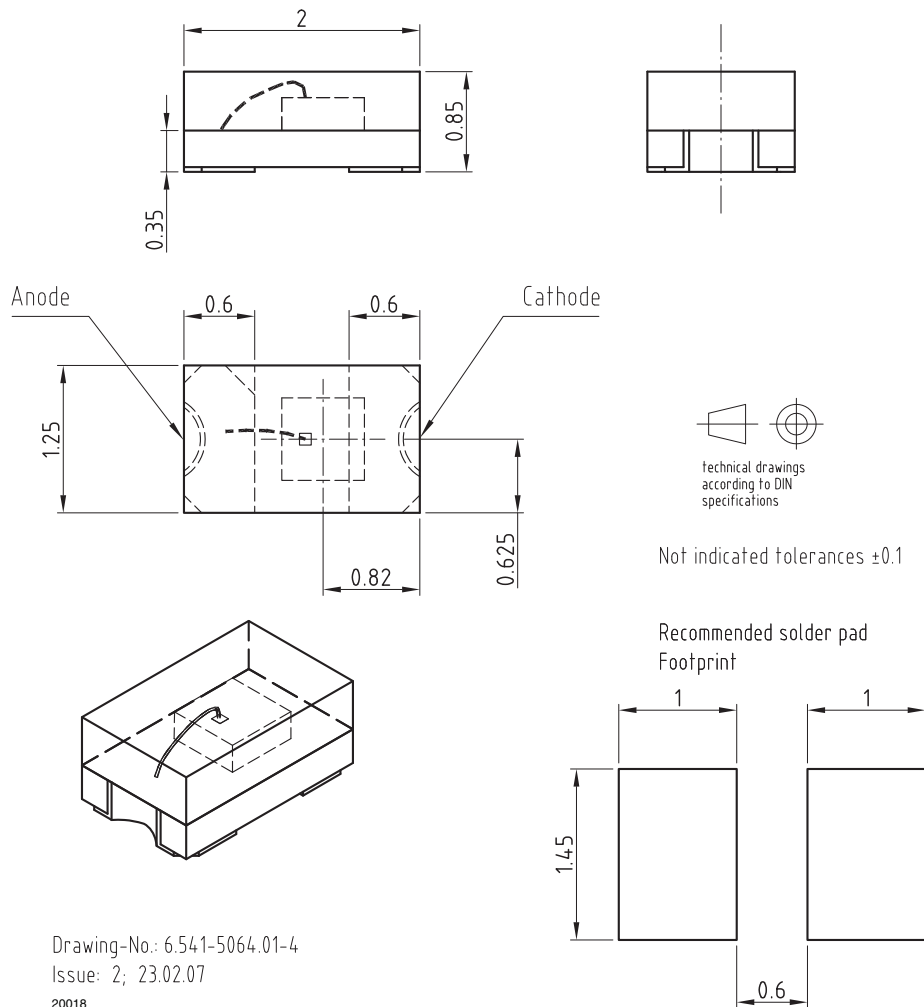
**FLOOR LIFE**

Time between soldering and removing from MBB must not exceed the time indicated in J-STD-020:  
 Moisture sensitivity: level 3  
 Floor life: 168 h  
 Conditions:  $T_{amb} < 30\text{ }^{\circ}\text{C}$ ,  $RH < 60\%$

**DRYING**

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at  $40\text{ }^{\circ}\text{C}$  ( $+ 5\text{ }^{\circ}\text{C}$ ),  $RH < 5\%$ .

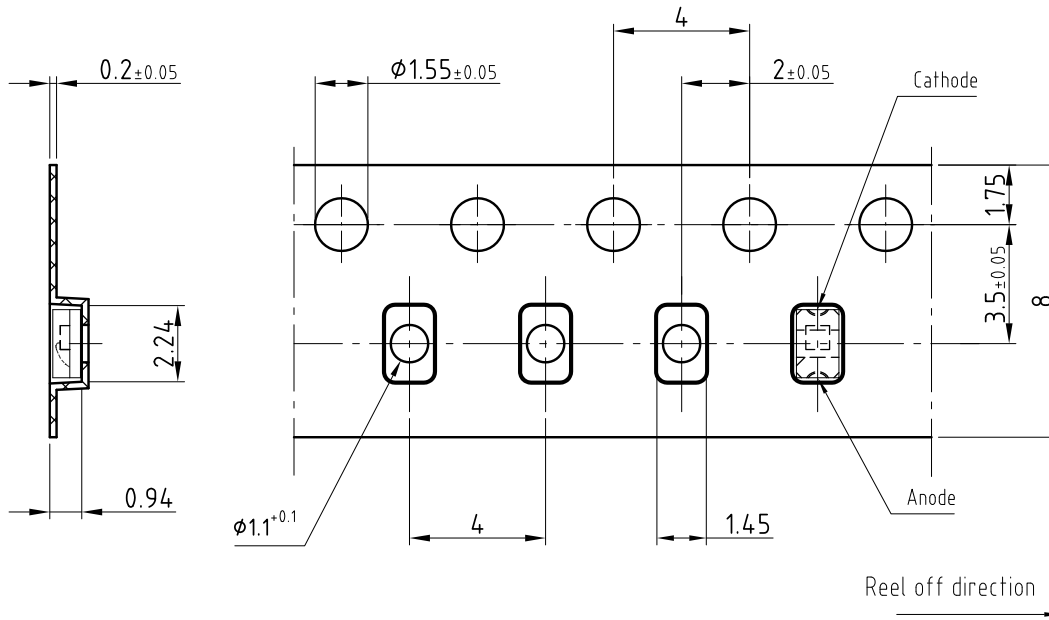
**PACKAGE DIMENSIONS** in millimeters



Drawing-No.: 6.541-5064.01-4  
 Issue: 2; 23.02.07  
 20018



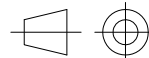
### BLISTER TAPE DIMENSIONS in millimeters



Drawing-No.: 9.700-5311.01-4

Issue: 1; 23.02.07

21501

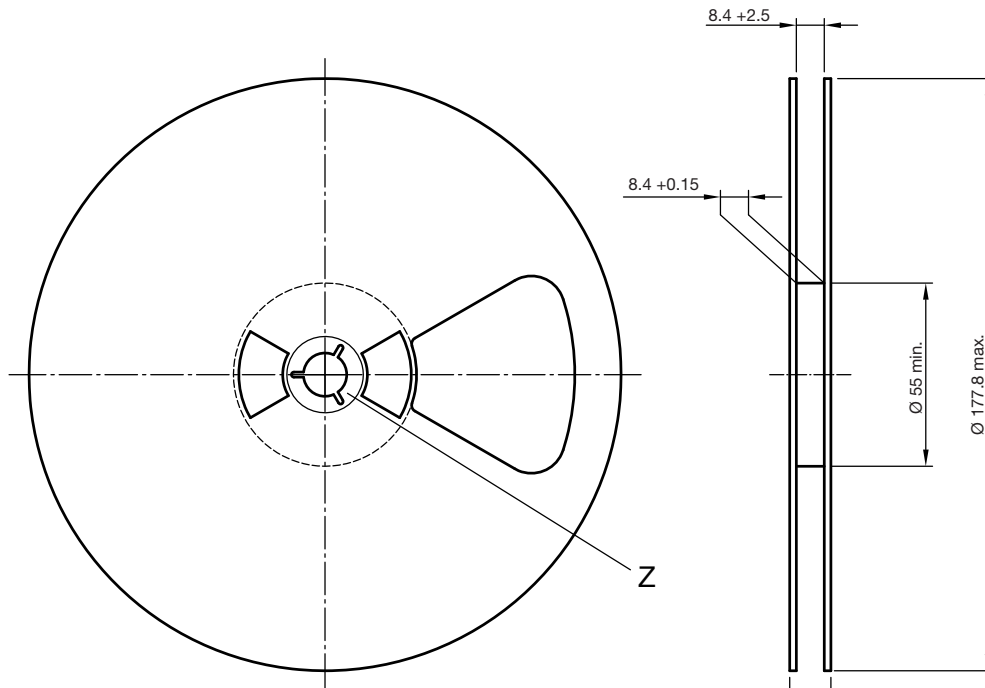


technical drawings  
according to DIN  
specifications

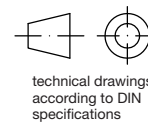
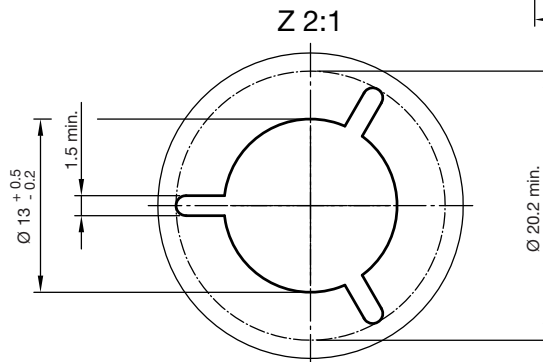
Not indicated tolerances ±0.1



REEL DIMENSIONS in millimeters



Form of the leave open of the wheel is supplier specific.



Drawing-No.: 9.800-5096.01-4  
 Issue: 2; 26.04.10  
 20875



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### Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: [info@moschip.ru](mailto:info@moschip.ru)

Skype отдела продаж:

moschip.ru

moschip.ru\_4

moschip.ru\_6

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